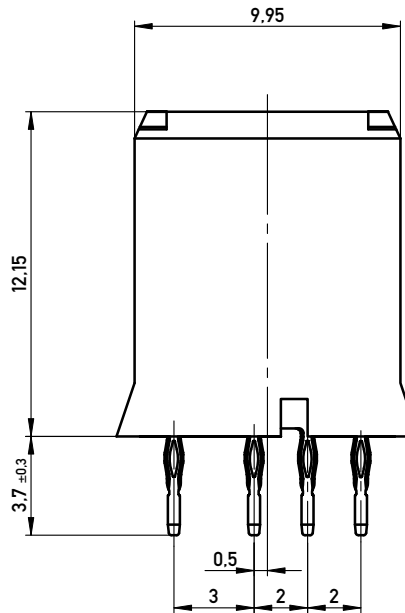


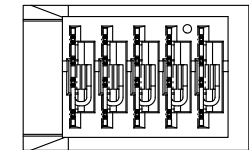
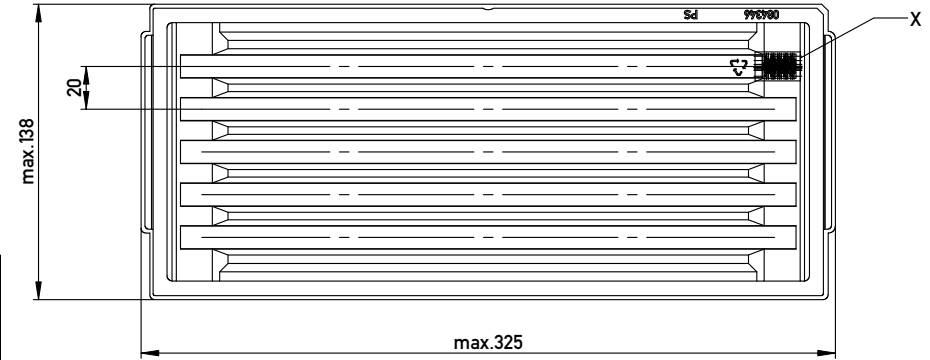
position A
position B
position C
position D
position E

0.75



Verpackt in Tray
VPE: 90 Stck.

tray packaging
packaging unit 90 pcs.



DETAIL X
MAßSTAB 2 : 1

Gehäuse / housing:
Kontakte / contacts:

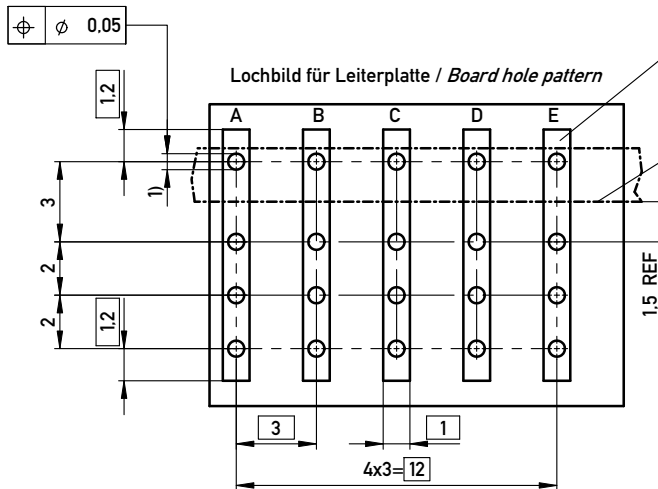
PBTP grau 30% GF / PBTP gray 30 %GF
Phosphor Bronze / phosphor bronze

Oberflächenbeschichtung / plating:
Kontaktbereich / mating area:
Anschlussbereich / termination:

2-3 µm Ni 1.2 µm Au
2-3 µm Ni 1 µm Sn matt

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printingcode Id.-No. 294997

Anforderungsstufe 1
class 1



Lochbild für Leiterplatte / Board hole pattern

Dieser Bereich muß gleiches
Potential auf LP-Oberfläche haben.

This area must have same
electrical potential on surface
of PCB

Oberkante Tochterkarte
to surface of daughtercard REF

1) $\varnothing 0,6 \pm 0,05$ Durchmesser des
metallisierten Loches
 $\varnothing 0,6 \pm 0,05$ Diameter of finished
plated-through hole

Schichtaufbau im metallisierten Loch siehe
Zeichnung 114406 oder 164062 Nr.1
Metal plating of plated-through hole see
drawing 114406 or 164062 no.1

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Information:		Tolerances		Scale	5:1
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Subject to modification without prior notice. Drawing will not be updated.				ERmet Federl. PM 5 Pol RC ERmet Female PM 5 Pin RC	
www.ERNI.com		244995		I A3	
Index	18.09.2007	Date		Class	
		Date		ERPM	